

LED SPECIFICATION

530PR2C



Features

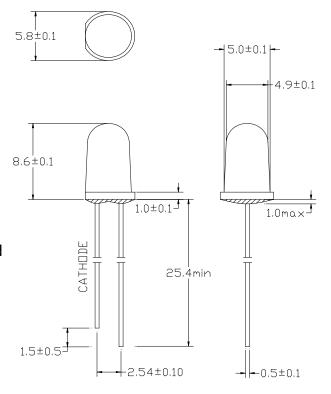
- Single color
- High bright output
- Low power consumption
- High reliability and long life

> Descriptions:

- Dice material: AlGaInP Hewlett Packard
- Emitting Color:

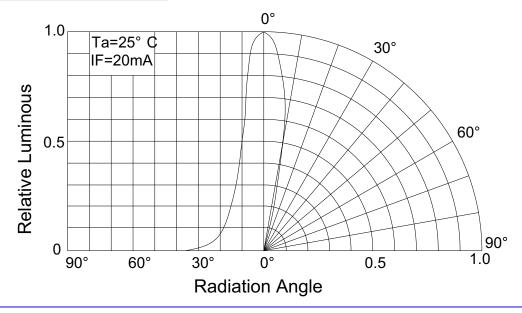
Super Bright RED

- Device Outline:
 - $\Phi\,\rm 5mm$ Round Type/ 5mm
- Lens Type:
 - Water Clear



- 1. All dimensions are millimeters
- 2. Tolerance is +/-0.25mm unless otherwise noted

> Directivity:





Absolute maximum ratings (Ta = 25°)

Parameter	Symbol	Test Condition	Va	Unit	
Falameter	Symbol	lest condition	Min.	Max.	Offic
Reverse Voltage	VR	IR = 30 µ A	5		V
Forward Current	lf			30	mA
Power Dissipation	Pd			75	mW
Pulse Current	Ipeak	Duty=0.1mS,1kHz		100	mA
Operating Temperature	Topr		-40	+85	°C
Storage Temperature	Tstr		-40	+100	°C

Electrical and optical characteristics (Ta = 25° C)

Parameter	Symbol Test Condition		Value			Unit	
			Min.	Тур.	Max.	Onic	
Forward Voltage	VF	IF = 20mA		V3~V5			
Reverse Current	IR	VR = 5V			30	μA	
Dominate Wavelength	λ d	IF = 20mA		R1~R3			
Spectral Line half-width	Δλ	IF = 20mA		20		nm	
Luminous Intensity	١v	IF = 20mA		W,X,Y			
Viewing Angle	2 θ 1/2	IF = 20mA	24		30	Deg.	



BRIGHTNESS BIN

Bin Code	IV(mcd)						
А	0-5.0	Н	37.2-52.0	Q	390-550	Х	41805860
В	5.0-7.0	J	52.0-72.8	R	550-770	Y	5860-8200
С	7.0-9.8	K	72.8-102	S	770-1100	Z1	8-10cd
D	9.8-13.7	L	102-145	Т	1100-1520	Z2	10-12cd
E	13.7-19.0	М	145-200	U	1520-2130	Z3	12-14cd
F	19.0-26.6	Ν	200-280	V	2130-3000	Z4	14-16cd
G	26.6-37.2	Р	280-390	W	3000-4180	Z5	16-18cd

WAVELENGTH BIN

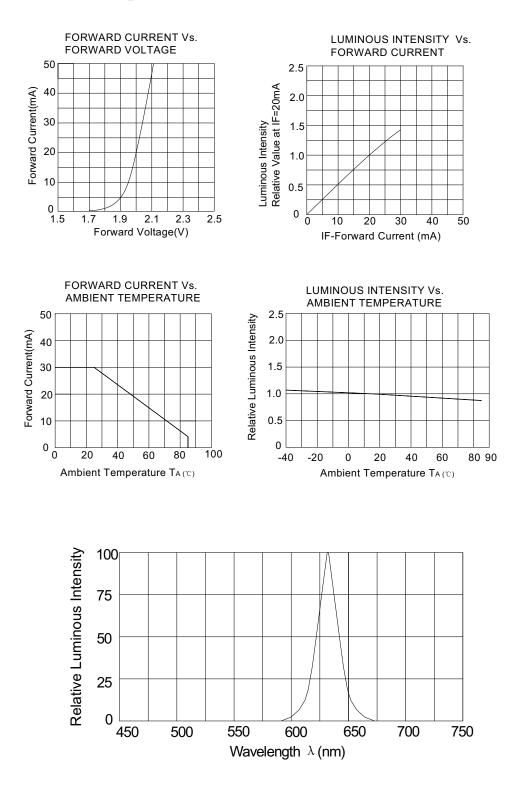
Ligth Col.	Bin Code	Wavel. (nm)	Ligth Col.	Bin Code	Wavel. (nm)
	B1	450-455		YG1	555-558
	B2	455-460		YG2	558-561
BLUE	B3	460-465	VELLOW	YG3	561-564
DLUL	B4	465-470	YELLOW GREEN	YG4	564-567
	B5	470-475	GHEEN	YG5	567-570
	B6	475-480		YG6	570-573
	G1	491-494		YG7	573-576
	G2	494-497		Y1	582-585
	G3	497-500		Y2	585-588
BLUE	G4	500-503	YELLOW	Y3	588-591
GREEN	G5	503-506		Y4	591-594
	G6	506-509		Y5	594-597
	G7	509-512		YO1	597-600
	G8	512-515	YELLOW	YO2	600-603
	G9	515-518	ORANGE	YO3	603-606
	G10	518-521		YO4	606-609
	G11	521-524	DUDE	01	609-612
	G12	524-527	PURE ORANGE	O2	612-615
	G13	527-530	ONANGE	O3	615-618
PURE GREEN	G14	530-533		R1	618-621
GREEN	G15	533-536	RED	R2	621-624
	G16	536-539		R3	624-627
	G17	539-542		R4	627-630
	G18	542-545		R5	630-633
	G19	545-548		R6	633-636

FORWARD VOLTAGE (VF) BIN

Bin Code	VF (V)						
V1	1.6-1.8	V5	2.4-2.6	V9	3.2-3.4	V13	4.0-4.2
V2	1.8-2.0	V6	2.6-2.8	V10	3.4-3.6	V14	4.2-4.4
V3	2.0-2.2	V7	2.8-3.0	V11	3.6-3.8	V15	4.4-4.6
V4	2.2-2.4	V8	3.0-3.2	V12	3.8-4.0	V16	4.6-4.8



Typical electrical/optical characteristic curves:

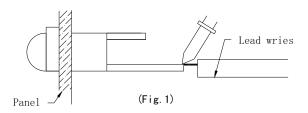




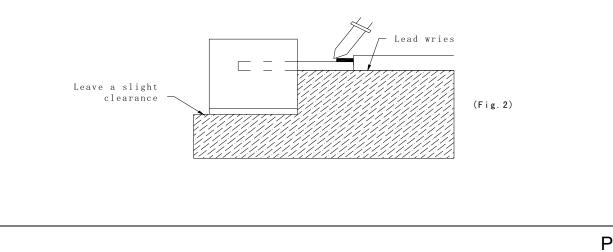
LED LAMP APPLICATION

•SOLDERIN	G	
METHOD	SOLDERING CONDITIONS	REMARK
DIP SOLDERING	Bath temperature: 260±5℃ Immersion time: with 5 sec	 Solder no closer than 3mm from the base of the package Using soldering flux," RESIN FLUX" is recommended.
SOLDERING IRON	Soldering iron: 30W or smaller Temperature at tip of iron: 260℃ or lower Soldering time: within 5 sec.	 During soldering, take care not to press the tip of iron against the lead. (To prevent heat from being transferred directly to the lead, hold the lead with a pair of tweezers while soldering

 When soldering the lead of LED in a condition that the package is fixed with a panel (See Fig.1), be careful not to stress the leads with iron tip.



2) When soldering wire to the lead, work with a Fig (See Fig.2) to avoid stressing the package.

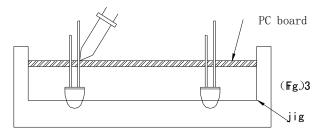




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LED LAMP APPLICATION

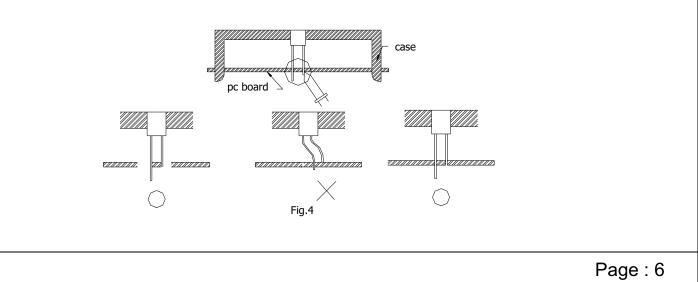
3) Similarly, when a jig is used to solder the LED to PC board, take care as much as possible to avoid steering the leads (See Fig.3).



- 4) Repositioning after soldering should be avoided as much as possible. If inevitable, be sure to preserve the soldering conditions with irons stated above: select a best-suited method that assures the least stress to the LED.
- Lead cutting after soldering should be performed only after the LED temperature has returned to normal temperature.

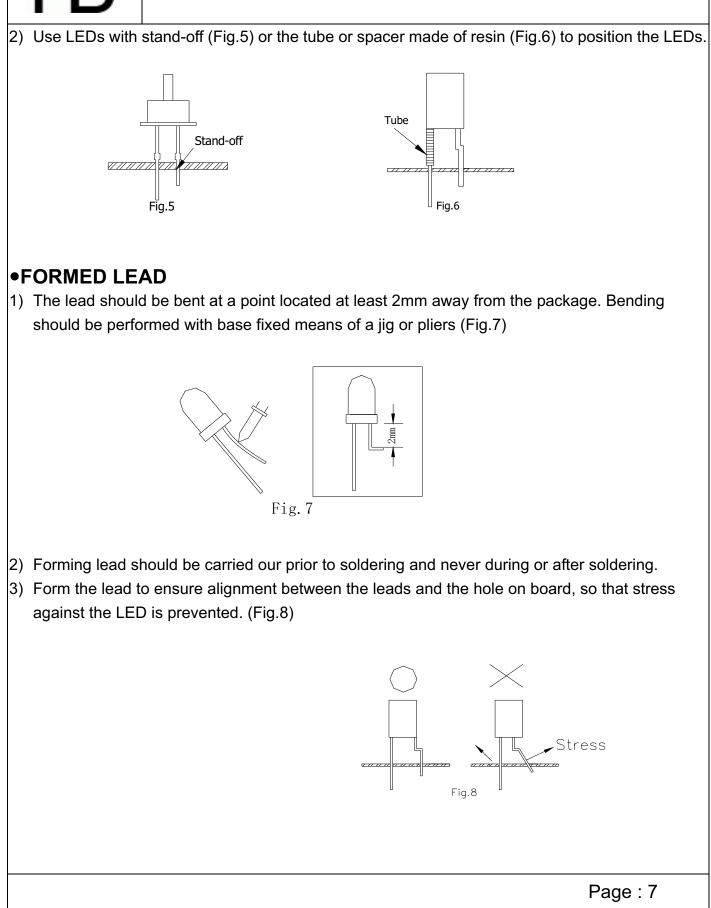
•LED MOUNTING METHOD

1) When mounting the LED by using a case, as shown Fig.4, ensure that the mounting holds on the PC board match the pitch of the leads correctly-tolerance of dimensions of the respective components including the LED should be taken into account especially when designing the case, PC board, etc. to prevent pitch misalignment between the leads and board holes, the diameter of the board holes should be slightly larger than the size of the lead. Alternatively, the shape of the holes should be made oval. (See Fig.4)





LED LAMP APPLICATION



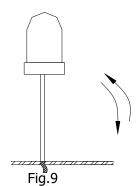


LED LAMP APPLICATION

•LEAD STRENGTH

1) Bend strength

Do not bend the lead more than twice. (Fig.9)



Tensile strength (@Room Temperature)
 If the force is 1kg or less, there will be no problem. (Fig.10)



•HANDLING PRECAUTIONS

Although rigid against vibration, the LEDs may damaged or scratched if dropped. So take care when handling.

•CHEMICAL RESISTANCE

- 1) Avoid exposure to chemicals as it may attack the LED surface and cause discoloration.
- When washing is required, refer to the following table for the proper chemical to be sued. (Immersion time: within 3 minutes at room temperature.)

SOLVENT	ADAPTABILITY			
Freon TE	\odot			
Chlorothene	\times			
Isopropyl Alcohol	\odot			
Thinner	\times			
Acetone	\times			
Trichloroethylene	\times			
\odot Usable \times Do not use.				

NOTE: Influences of ultrasonic cleaning of the LED resin body differ depending on such factors as the oscillator output, size of the PC board and the way in which the LED is mounted. Therefore, ultrasonic cleaning should only be performed after confirming there is no problem by conducting a test under practical.



Experiment Item:

	Test Condition				
Item	Lamp & IR	Reference Standard			
OPERATION LIFE	Ta : 25±5℃ IF= 20mA RH : <=60%RH ① DYNAMIC:100mA 1ms 1/10 duty ② STATIC STATE: IF=20mA TEST TIME: 168HRS (-24HRS [,] +24HRS) 500HRS (-24HRS [,] +24HRS) 1000HRS (-24HRS [,] +72HRS)	MIL-STD-750:1026 MIL-STD-883:1005 JIS C 7021:B-1			
HIGH TEMPERATURE HIGH HUMIDITY STORAGE	Ta: 65℃±5℃ RH: 90~95%RH TEST TIME:240HRS±2HRS	MIL-STD-202:103B JIS C 7021:B-1			
TEMPERATURE CYCLING	105℃~25℃~-55℃~25℃ 30min 5min 30min 5min 10CYCLES	MIL-STD-202 : 107D MIL-STD-750 : 1051 MIL-STD-883 : 1010 JIS C 7021 : A-4			
THERMAL SHOCK	105℃±5℃~-55℃±5℃ 10min 10min 10CYCLES	MIL-STD-202:107D MIL-STD-750:1051 MIL-SYD-883:1011			
SOLDER RESISTANCE	T,sol:260℃±5℃ DWELL TIME:10±lsec	MIL-STD-202 : 210A MIL-STD-750-2031 JIS C 7021 : A-1			
SOLDERABILITY	T,sol:230℃±5℃ DWELL TIME:5±lsec	MIL-STD-202 : 208D MIL-STD-750 : 2026 MIL-STD-883 : 2003 JIS C 7021 : A-2			
Drive Method					
Circuit mo	odel A Circuit model B				
(A)Recommended cire	cuit.	Page : 9			

(B)The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.